

1                   ABSTRACT OF THE DISCLOSURE

2                   A semiconductor workpiece holder for use in processing a  
3                   semiconductor workpiece includes a workpiece support operatively  
4                   mounted to support a workpiece in position for processing. A finger  
5                   assembly is operatively mounted upon the workpiece support and  
6                   includes a finger tip. The finger assembly is movable between an  
7                   engaged position in which the finger tip is engaged against the  
8                   workpiece, and a disengaged position in which the finger tip is moved  
9                   away from the workpiece. Preferably, at least one electrode forms part  
10                  of the finger assembly and includes an electrode contact for contacting  
11                  a surface of said workpiece. At least one protective sheath covers at  
12                  least some of the electrode contact. According to one aspect of the  
13                  invention, a sheathed electrode having a sheathed electrode tip is  
14                  positioned against a semiconductor workpiece surface in a manner  
15                  engaging the workpiece surface with said sheathed electrode tip. A seal  
16                  is formed about the periphery of the electrode tip, and with the  
17                  electrode tip engaging the workpiece, a desired electrical contact is  
18                  made to the workpiece. Thereafter, the workpiece is exposed to  
19                  desired semiconductor processing conditions.